# Triple 2-3-2-Input OR/NOR Gate

### Description

The MC10H105 is a triple 2-3-2-input OR/NOR gate. This MECL  $10H^{\text{TM}}$  part is a functional/pinout duplication of the standard MECL  $10K^{\text{TM}}$  family part, with 100% improvement in propagation delay, and no increases in power-supply current.

#### **Features**

- Propagation Delay, 1.0 ns Typical
- Power Dissipation 25 mW/Gate (same as MECL 10K)
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K Compatible
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

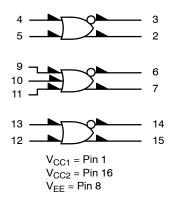
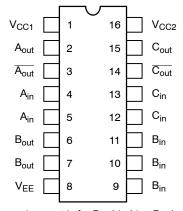


Figure 1. Logic Diagram



Pin assignment is for Dual-in-Line Package.

Figure 2. Pin Assignment



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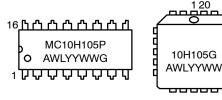
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PDIP-16 P SUFFIX CASE 648-08 PLLC-20 FN SUFFIX CASE 775-02

# **MARKING DIAGRAMS\***



PDIP-16

PLLC-20

A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G = Pb-Free Package

# **ORDERING INFORMATION**

Device	Package	Shipping
MC10H105FNG	PLLC-20 (Pb-Free)	46 Units / Tube
MC10H105PG	PDIP-16 (Pb-Free)	25 Units / Tube

1

<sup>\*</sup>For additional marking information, refer to Application Note <u>AND8002/D</u>.

**Table 1. MAXIMUM RATINGS** 

Symbol	Characteristic	Rating	Unit
V <sub>EE</sub>	Power Supply (V <sub>CC</sub> = 0)	-8.0 to 0	Vdc
VI	Input Voltage (V <sub>CC</sub> = 0)	0 to V <sub>EE</sub>	Vdc
l <sub>out</sub>	Output Current Continuous Surge	50 100	mA
T <sub>A</sub>	Operating Temperature Range	0 to +75	°C
T <sub>stg</sub>	Storage Temperature Range Plastic Ceramic	−55 to +150 −55 to +165	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 2. ELECTRICAL CHARACTERISTICS (V $_{EE}$  =  $-5.2~V~\pm 5\%$ ) (Note 1)

		<b>0</b> °		<b>25</b> °		<b>75</b> °		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
Ι <sub>Ε</sub>	Power Supply Current	_	23	_	21	_	23	mA
I <sub>inH</sub>	Input Current High	_	425	_	265	_	265	μΑ
I <sub>inL</sub>	Input Current Low	0.5	-	0.5	_	0.3	_	μΑ
V <sub>OH</sub>	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V <sub>OL</sub>	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
V <sub>IH</sub>	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V <sub>IL</sub>	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

<sup>1.</sup> Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50 Ω resistor to –2.0 V.

**Table 3. AC CHARACTERISTICS** 

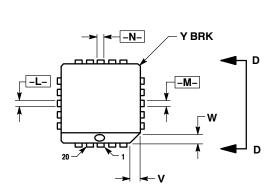
		<b>0</b> °		<b>25</b> °		<b>75</b> °		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
t <sub>pd</sub>	Propagation Delay	0.43	1.2	0.4	1.2	0.4	1.3	ns
t <sub>r</sub>	Rise Time	0.5	1.5	0.5	1.6	0.5	1.7	ns
t <sub>f</sub>	Fall Time	0.5	1.5	0.5	1.6	0.5	1.7	ns

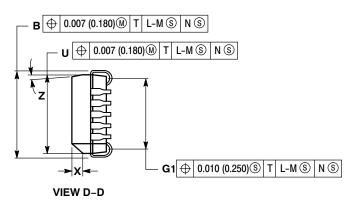
NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

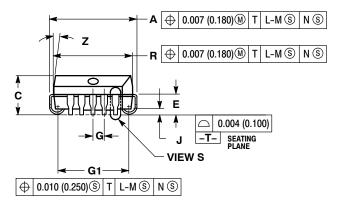
#### PACKAGE DIMENSIONS

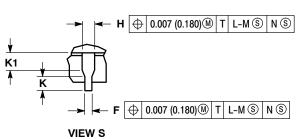
# **20 LEAD PLLC FN SUFFIX**

CASE 775-02 ISSUE F









- 1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M,
- 2. DIMENSIONS IN INCHES.
  3. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD

  OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

- PARTING LINE.

  4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

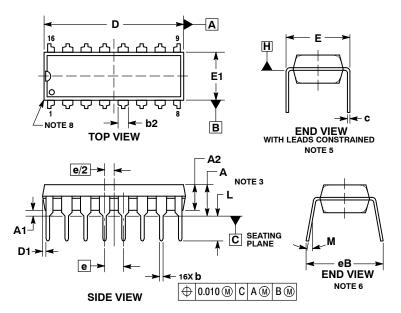
  5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

  6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
  7. DIMENSION H DOES NOT INCLUDE DAMBAR
- DIMENSION OF INTRUSION. THE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.385	0.395	9.78	10.03	
В	0.385	0.395	9.78	10.03	
С	0.165	0.180	4.20	4.57	
E	0.090	0.110	2.29	2.79	
F	0.013	0.021	0.33	0.53	
G	0.050	BSC	1.27 BSC		
н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.350	0.356	8.89	9.04	
U	0.350	0.356	8.89	9.04	
V	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
Х	0.042	0.056	1.07	1.42	
Υ		0.020		0.50	
Z	2°	10 °	2°	10 °	
G1	0.310	0.330	7.88	8.38	
K1	0.040		1.02		

#### PACKAGE DIMENSIONS

### PDIP-16 P SUFFIX CASE 648-08 ISSUE V



#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 1994.
- 2. CONTROLLING DIMENSION: INCHES.
- DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
   DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH
- DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH.
   DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM
- DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR TO DATUM C.
- 6. DIMENSION 6B IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
- DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE LEADS, WHERE THE LEADS EXIT THE BODY.
- 8. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE CORNERS)

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α		0.210		5.33	
A1	0.015		0.38		
A2	0.115	0.195	2.92	4.95	
b	0.014	0.022	0.35	0.56	
b2	0.060	TYP	1.52	TYP	
С	0.008	0.014	0.20	0.36	
D	0.735	0.775	18.67	19.69	
D1	0.005		0.13		
E	0.300	0.325	7.62	8.26	
E1	0.240	0.280	6.10	7.11	
е	0.100	BSC	2.54 BSC		
eB		0.430		10.92	
L	0.115	0.150	2.92	3.81	
M		10°		10°	

STYLE 1	:	STYLE 2	:
PIN 1.	CATHODE	PIN 1.	COMMON DRAIN
2.	CATHODE	2.	COMMON DRAIN
3.	CATHODE	3.	COMMON DRAIN
4.	CATHODE	4.	COMMON DRAIN
5.	CATHODE	5.	COMMON DRAIN
6.	CATHODE	6.	COMMON DRAIN
7.	CATHODE	7.	COMMON DRAIN
8.	CATHODE	8.	COMMON DRAIN
9.	ANODE	9.	GATE
10.	ANODE	10.	SOURCE
11.	ANODE	11.	GATE
12.	ANODE	12.	SOURCE
13.	ANODE	13.	GATE
14.		14.	
15.		15.	
16.	ANODE	16.	SOURCE

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